

2SA2162

Silicon PNP epitaxial planar type

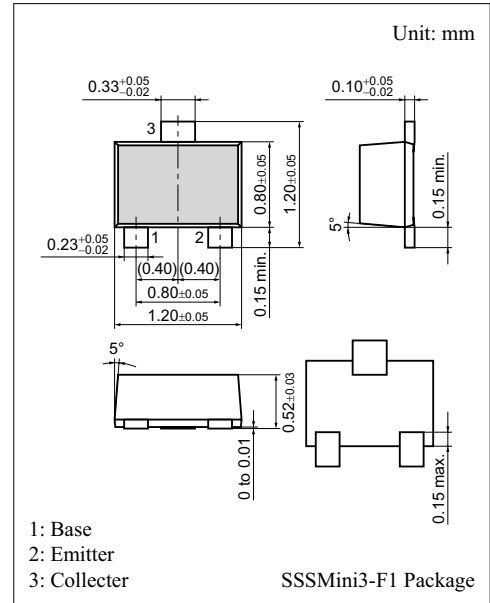
For general amplification
Complementary to 2SC6036

■ Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- SSS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-15	V
Collector-emitter voltage (Base open)	V_{CEO}	-12	V
Emitter-base voltage (Collector open)	V_{EBO}	-5	V
Collector current	I_C	-500	mA
Peak collector current	I_{CP}	-1	A
Collector power dissipation	P_C	100	mW
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

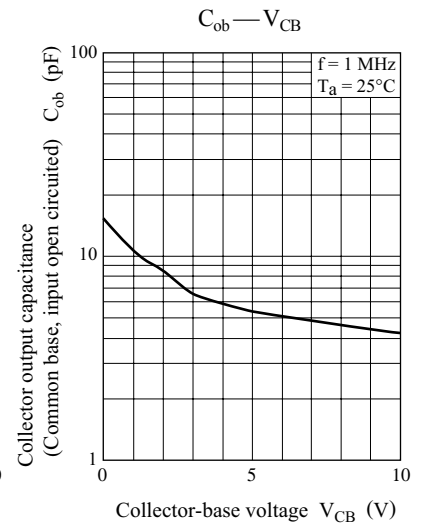
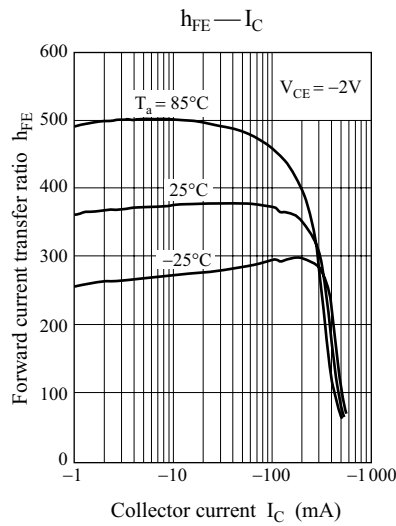
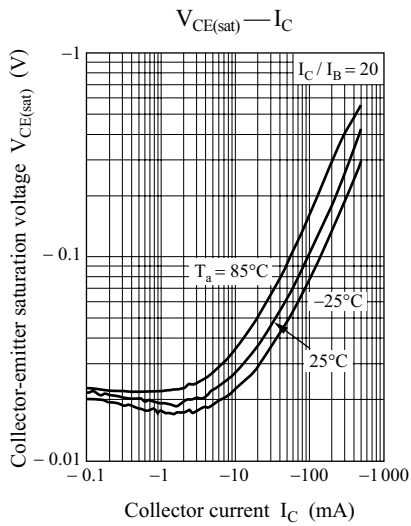
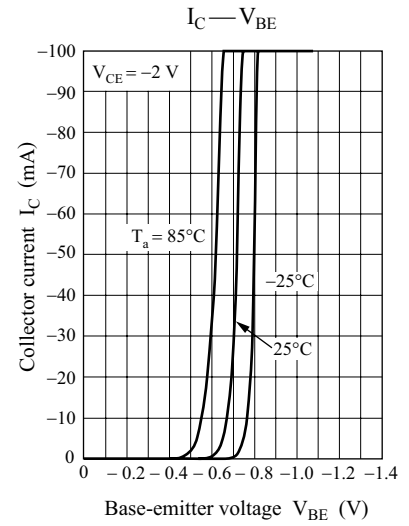
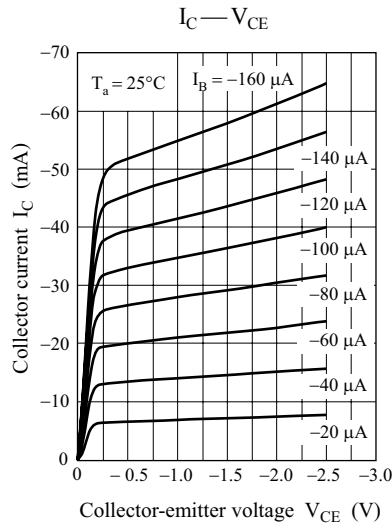
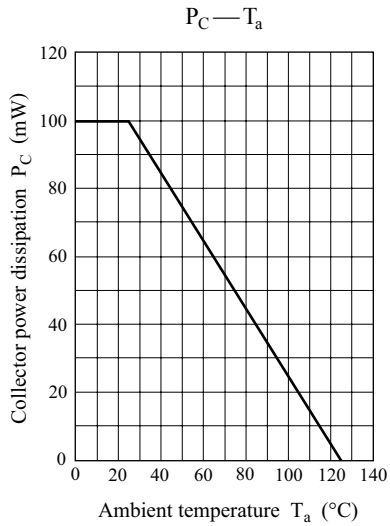


Marking Symbol : 2U

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10 \mu\text{A}, I_E = 0$	-15			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -1 \text{ mA}, I_B = 0$	-12			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu\text{A}, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -10 \text{ V}, I_E = 0$			-0.1	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = -2 \text{ V}, I_C = -10 \text{ mA}$	270		680	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -200 \text{ mA}, I_B = -10 \text{ mA}$			-250	mV
Transition frequency	f_T	$V_{CB} = -2 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10 \text{ V}, f = 1 \text{ MHz}$		4.5		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



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